
Admission Brochure

2027 Fall International Master Program in Advanced Semiconductor Packaging & Testing (INTENSE Program-ASE)	
Degree	Master
College	College of Engineering
Begin Term	Fall (Enroll in September)
Language proficiency	English proficiency certificate/proof required • TOEIC 550 or above CEFR B1 Chinese proficiency certificate/proof required • Both Listening and Reading at least at level A2 before the end of the 3rd semester
Financial support	An English bank deposit statement issued within three months of at least US\$3,000 (~ NT\$90,000)

Application documents	• The highest-level degree diploma • The highest degree's full transcript of records • Financial statement • Recommendation letter x 2 • Statement of Purpose • Declaration of Nationality Form • Passport (if available) • Taiwan Alien Resident Certificate (ARC) (if available)
Documents required by department	• English personal statement (up to 1000 words) • Research plan (up to 3000 words) • English proficiency certificate • Other related references (ex. publications, journal papers, conference papers and technical reports)
Interview / Oral exam	Online interview with Collaborating Companies
Written exam	No
Additional notes	<u>Obligations</u> 1. Students receiving industry-academia scholarships from the National Development Fund, Taiwan are obligated to stay and work in Taiwan for a corresponding period based on the number of years they received the scholarship. 2. Those receiving a one-year industry-academia scholarship have a one-year obligation to stay and work in Taiwan, while those receiving a two-year industry-academia scholarship have a two-year obligation to stay and work in Taiwan.

***Notes

1. If a student withdraws from the program midway during the academic term due to personal reasons, such as applying for transfer to another program, changing majors, taking a leave of absence, or returning to their home country, and after counseling from the school, still decides to give up continuing in the program, or if the school, in accordance with its regulations, decides to withdraw or expel the student, **the student is required to fully repay any industry-academia scholarship funds received.**
2. If a student chooses not to work for the collaborating company or in a related industry field after graduation, and despite counseling from the school, **the student is required to fully repay any industry-academia scholarship funds received.**
3. If a student, after graduating and entering employment, violates company regulations leading to the lawful termination of the employment contract, and despite counseling from the school, **the student should repay the industry-academia scholarship funds proportionally based on the number of months not employed;** for a period less than one month, it will be counted as one month.
4. During the period of fulfilling the employment obligation after graduation, students are required to **work in a position within domestic collaborating companies in Taiwan.** They are not allowed to be dispatched to work at overseas branches or be employed by overseas Taiwanese-owned companies. **If a student fails to comply with the requirement of domestic employment, they should repay the industry-academia scholarship funds proportionally based on the number of months not employed in**

	Taiwan; for a period less than one month, it will be counted as one month.
Scholarship	1. National Development Fund, Taiwan: (1) NT 100,000 for the first year. (2) If you pass the Chinese proficiency test -Listening and Reading at least at level A2, you can get NT 100,000 for the second year. 2. Matching funding from Company: NT 240,000 / 2 years (NT 10,000 per month for up to 2 years). 3. Administrative fee: (1) The administrative fees have a maximum limit of NT\$10,000. (2) The one-way airfare is based on the most direct economy class flight to Taiwan. (Reimbursed with a maximum limit of NT\$9,000)
Introduction	This new program is designed to meet the growing global demand for talent in the semiconductor packaging and testing industry, with strong collaboration between National Chung Cheng University (CCU) and industry partners- ASE Group. Through industry–academia cooperation programs, the initiative jointly recruits outstanding international students and provides a structured training pathway that integrates academic learning with practical industry experience. The program focuses on advanced semiconductor packaging and testing technologies, emphasizing real-world manufacturing processes, quality assurance, and system-level integration. By leveraging advances in heterogeneous integration, automation, artificial intelligence, and smart manufacturing, the program aims to cultivate professionals capable of supporting next-generation semiconductor assembly, packaging, and testing operations. Core technical areas include: • Advanced Semiconductor Packaging Technologies (including SiP and heterogeneous integration)

	• Semiconductor Testing, Reliability, and Failure Analysis • Packaging Process Integration and Manufacturing Optimization • Intelligent Packaging and Testing Systems with AI Applications
Curriculum planning	This program is an all-English graduate program designed to attract, educate, and prepare students for leading roles in the field of Semiconductor Packaging and Testing. The program is developed in close collaboration with industry partners- ASE Group, through industry-academia cooperation and dedicated corporate-sponsored cohort programs. The program emphasizes the integration of multidisciplinary knowledge, including advanced semiconductor packaging technologies, testing and reliability engineering, materials science, automation, artificial intelligence, and smart manufacturing systems. Through a strong combination of theoretical learning and hands-on industry training, students will develop the technical expertise and system-level understanding required for semiconductor assembly, packaging process integration, testing, and quality assurance. The program also aims to cultivate problem-solving and professional competencies to support innovation and excellence in next-generation semiconductor packaging and testing industries.
Future map	Employment career: Students should work in Taiwan after graduation for at least 2 years in a collaborating Company. *** <u>Collaborating Company (ASE)</u> Advanced Semiconductor Engineering, Inc. 日月光半導體製造股份有限公司 (10 positions) : Process Engineer / 10 positions https://ase.aseglobal.com/

Website	This Program Website https://aimhi.ccu.edu.tw/p/404-1017-53935.php?Lang=zh-tw AIM-HI https://aimhi.ccu.edu.tw/index.php?Lang=en
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Getting to CCU



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